

## FEATURES

- Member of the Texas Instruments Widebus+™ Family
- Operates From 1.65 V to 3.6 V
- Max  $t_{pd}$  of 3 ns at 3.3 V
- $\pm 24$ -mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This 32-bit buffer/driver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH32244 is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as eight 4-bit buffers, four 8-bit buffers, two 16-bit buffers, or one 32-bit buffer. It provides true outputs and symmetrical active-low output-enable ( $\overline{OE}$ ) inputs.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	LFBGA - GKE	Tape and reel	SN74ALVCH32244KR	ACH244
	LFBGA - ZKE (Pb-free)		74ALVCH32244ZKER	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (each 4-bit buffer)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus+ is a trademark of Texas Instruments.

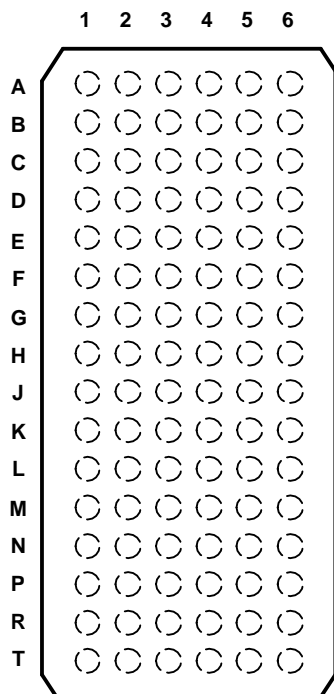
# SN74ALVCH32244

## 32-BIT BUFFER/DRIVER

### WITH 3-STATE OUTPUTS

SCES281D—OCTOBER 1999—REVISED SEPTEMBER 2004

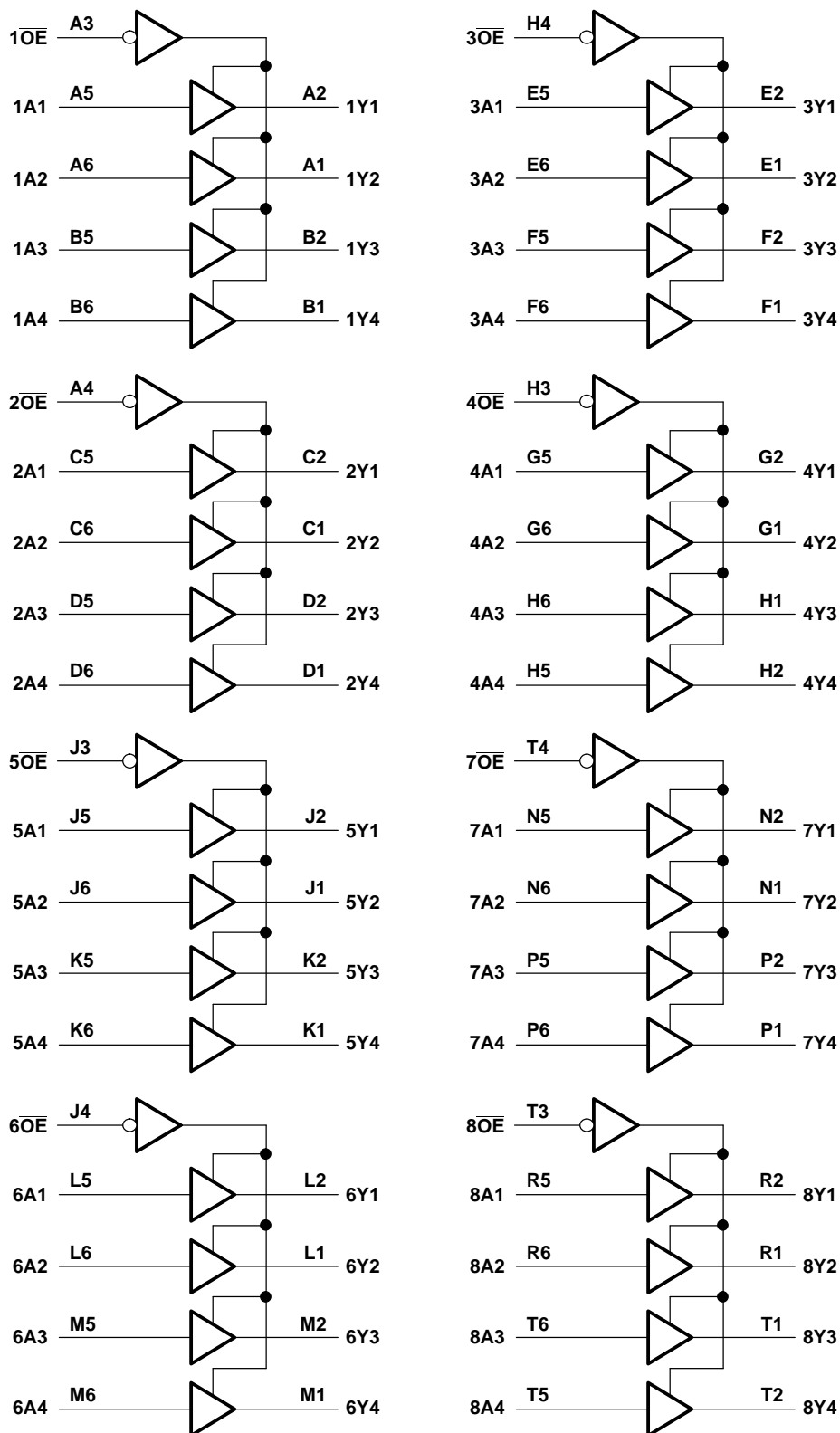
**GKE OR ZKE PACKAGE  
(TOP VIEW)**



**TERMINAL ASSIGNMENTS**

	1	2	3	4	5	6
<b>A</b>	1Y2	1Y1	1 $\overline{\text{OE}}$	2 $\overline{\text{OE}}$	1A1	1A2
<b>B</b>	1Y4	1Y3	GND	GND	1A3	1A4
<b>C</b>	2Y2	2Y1	V <sub>CC</sub>	V <sub>CC</sub>	2A1	2A2
<b>D</b>	2Y4	2Y3	GND	GND	2A3	2A4
<b>E</b>	3Y2	3Y1	GND	GND	3A1	3A2
<b>F</b>	3Y4	3Y3	V <sub>CC</sub>	V <sub>CC</sub>	3A3	3A4
<b>G</b>	4Y2	4Y1	GND	GND	4A1	4A2
<b>H</b>	4Y3	4Y4	4 $\overline{\text{OE}}$	3 $\overline{\text{OE}}$	4A4	4A3
<b>J</b>	5Y2	5Y1	5 $\overline{\text{OE}}$	6 $\overline{\text{OE}}$	5A1	5A2
<b>K</b>	5Y4	5Y3	GND	GND	5A3	5A4
<b>L</b>	6Y2	6Y1	V <sub>CC</sub>	V <sub>CC</sub>	6A1	6A2
<b>M</b>	6Y4	6Y3	GND	GND	6A3	6A4
<b>N</b>	7Y2	7Y1	GND	GND	7A1	7A2
<b>P</b>	7Y4	7Y3	V <sub>CC</sub>	V <sub>CC</sub>	7A3	7A4
<b>R</b>	8Y2	8Y1	GND	GND	8A1	8A2
<b>T</b>	8Y3	8Y4	8 $\overline{\text{OE}}$	7 $\overline{\text{OE}}$	8A4	8A3

LOGIC DIAGRAM (POSITIVE LOGIC)



# SN74ALVCH32244

## 32-BIT BUFFER/DRIVER

### WITH 3-STATE OUTPUTS

SCES281D–OCTOBER 1999–REVISED SEPTEMBER 2004

#### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$	-50	mA
$I_O$	Continuous output current		±50	mA
	Continuous current through each $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	GKE/ZKE package		40 °C/W
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

#### RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
$V_I$	Input voltage		0	$V_{CC}$	V
$V_O$	Output voltage		0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65 \text{ V}$		-4	mA
		$V_{CC} = 2.3 \text{ V}$		-8	
		$V_{CC} = 2.7 \text{ V}$		-12	
		$V_{CC} = 3 \text{ V}$		-24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65 \text{ V}$		4	mA
		$V_{CC} = 2.3 \text{ V}$		8	
		$V_{CC} = 2.7 \text{ V}$		12	
		$V_{CC} = 3 \text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
$T_A$	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
		I <sub>OH</sub> = -4 mA	1.65 V	1.2			
		I <sub>OH</sub> = -8 mA	2.3 V	1.7			
		I <sub>OH</sub> = -12 mA	2.7 V	2.2			
			3 V	2.4			
		I <sub>OH</sub> = -24 mA	3 V	2.2			
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2			V
		I <sub>OL</sub> = 4 mA	1.65 V	0.45			
		I <sub>OL</sub> = 8 mA	2.3 V	0.7			
		I <sub>OL</sub> = 12 mA	2.7 V	0.4			
		I <sub>OL</sub> = 24 mA	3 V	0.55			
I <sub>I</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5			μA
I <sub>I(hold)</sub>		V <sub>I</sub> = 0.58 V	1.65 V	25			μA
		V <sub>I</sub> = 1.07 V	1.65 V	-25			
		V <sub>I</sub> = 0.7 V	2.3 V	45			
		V <sub>I</sub> = 1.7 V	2.3 V	-45			
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V	3 V	-75			
		V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V	±500			
I <sub>OZ</sub>		V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10			μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	80			μA
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750			μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	3			pF
	Data inputs			6			
C <sub>O</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V	7			pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	(1)	(1)	1	3.7	3.6		1	3	ns
t <sub>en</sub>	OE	Y	(1)	(1)	1	5.7	5.4		1	4.4	ns
t <sub>dis</sub>	OE	Y	(1)	(1)	1	5.2	4.6		1	4.1	ns

(1) This information was not available at the time of publication.

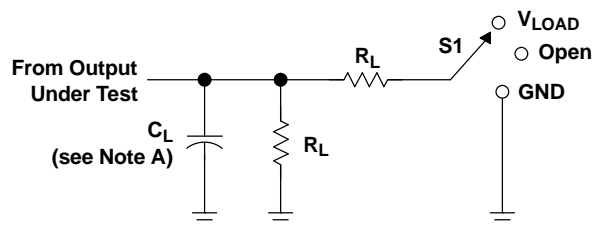
## OPERATING CHARACTERISTICS

T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
			TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance	C <sub>L</sub> = 0, f = 10 MHz	(1)	16	19	pF
	Outputs enabled		(1)	4	5	

(1) This information was not available at the time of publication.

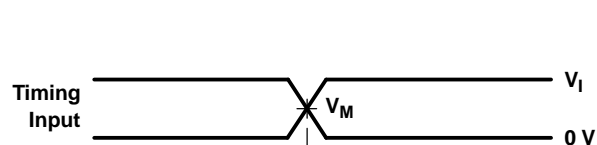
## PARAMETER MEASUREMENT INFORMATION



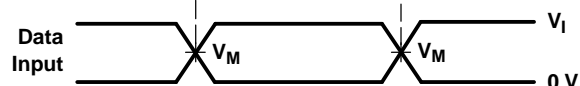
LOAD CIRCUIT

TEST	S1
$t_{pd}$ $t_{PLZ}/t_{PZL}$ $t_{PHZ}/t_{PZH}$	Open $V_{LOAD}$ GND

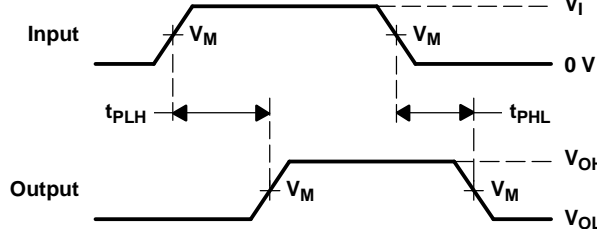
$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



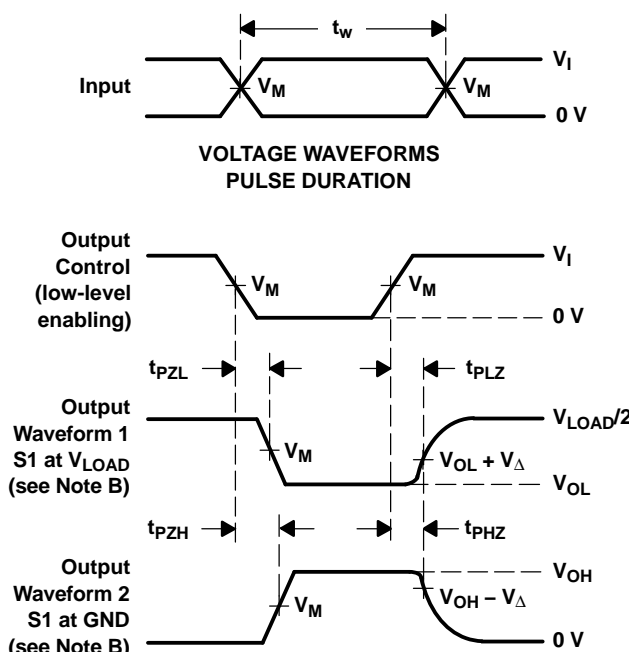
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
74ALVCH32244ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	ACH244	<a href="#">Samples</a>
SN74ALVCH32244KR	NRND	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR	-40 to 85	ACH244	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH32244ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74ALVCH32244KR	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1



## TAPE AND REEL BOX DIMENSIONS

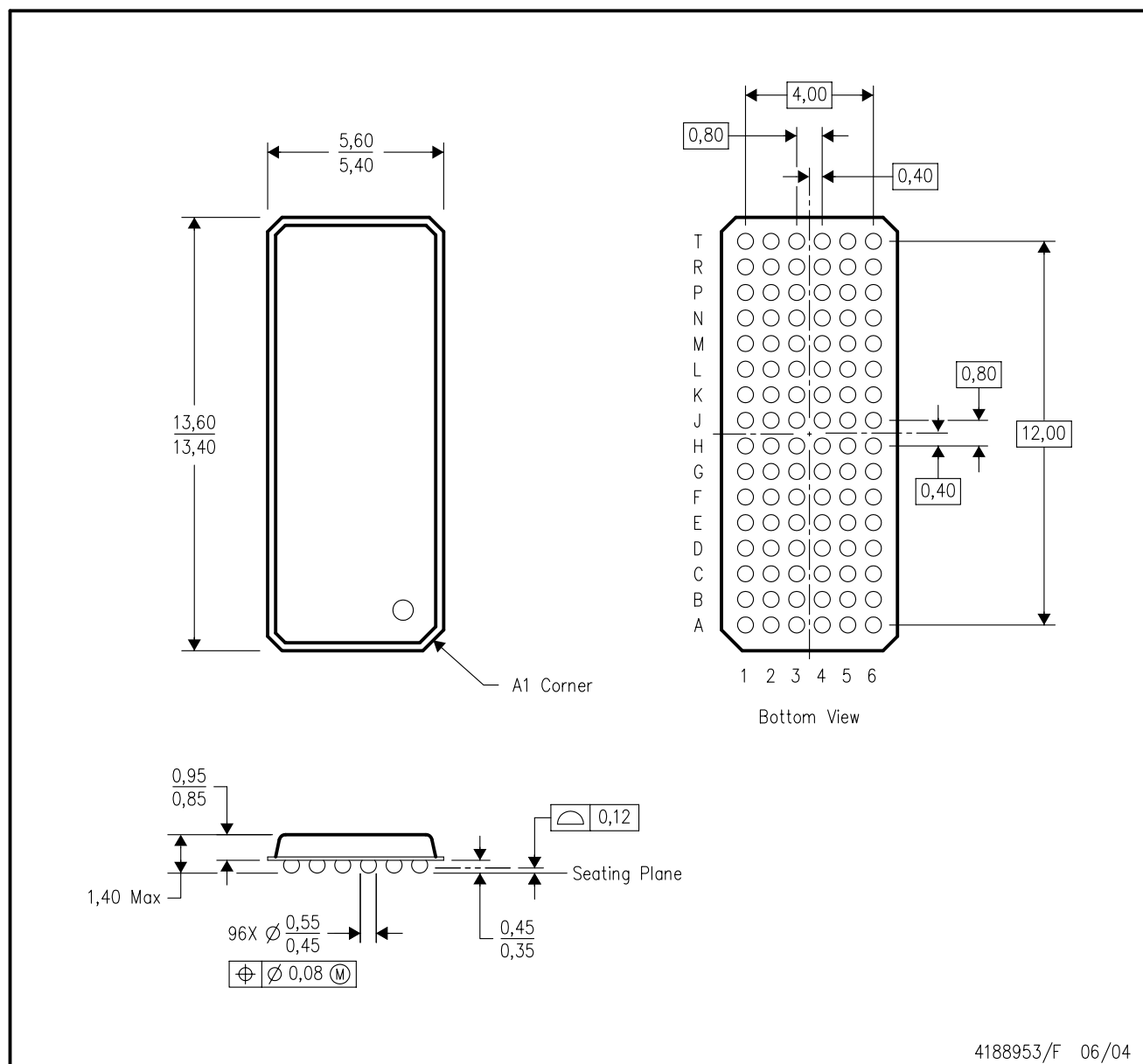


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH32244ZKER	LFBGA	ZKE	96	1000	336.6	336.6	41.3
SN74ALVCH32244KR	LFBGA	GKE	96	1000	336.6	336.6	41.3

GKE (R-PBGA-N96)

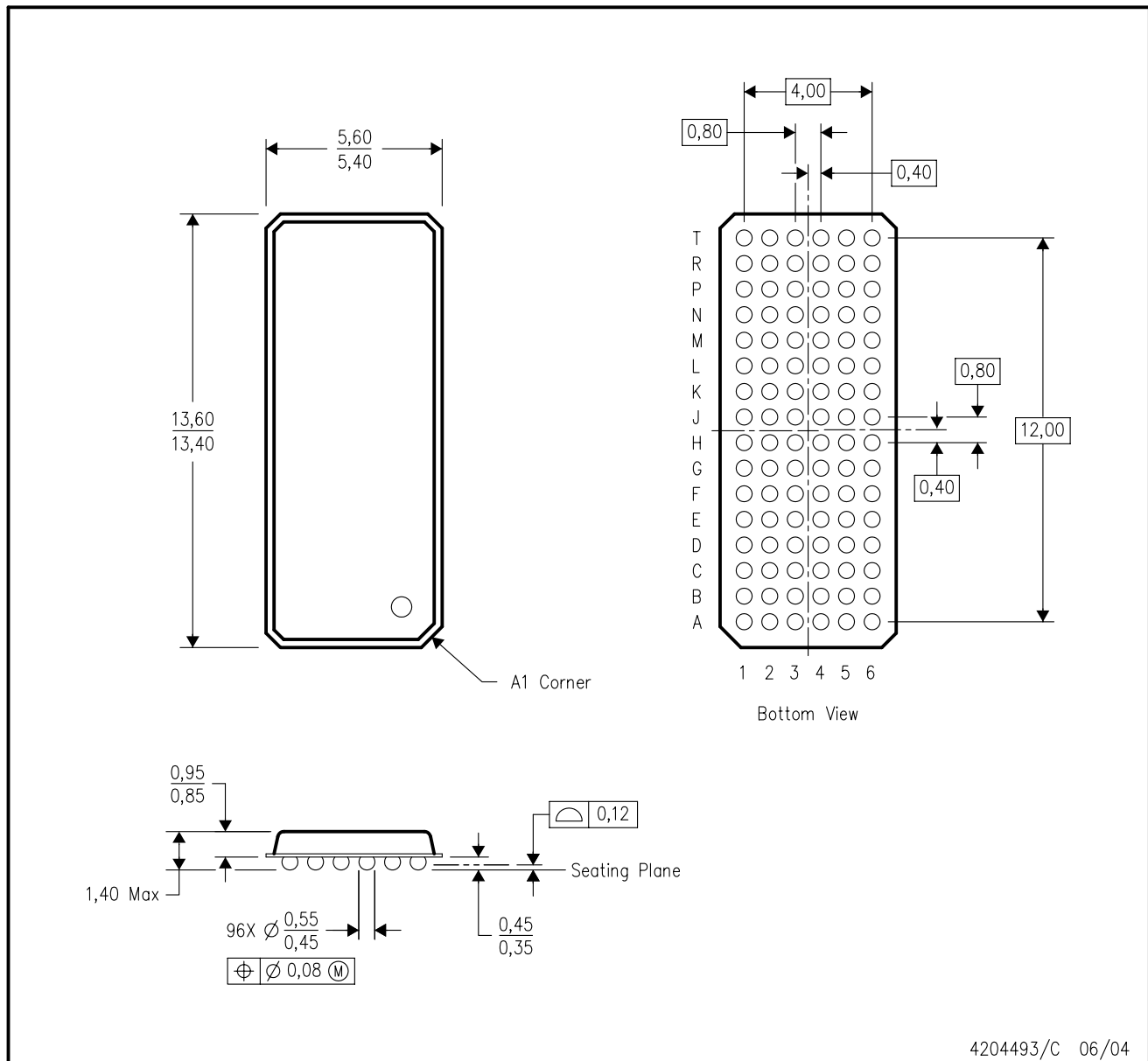
## PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.  
C. Falls within JEDEC MO-205 variation CC.  
D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)